

7926402

JC03 Rec'd PCT/PTO 26 OCT 2001

215245US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

#40  
REAL

IN RE APPLICATION OF :

ERIC PILAT

: ATTN: APPLICATION DIVISION

SERIAL NO: NEW U.S. PCT APPLN :  
(Based on PCT/FR00/01097)

FILED: HEREWITH :

FOR: METHOD FOR THE MAKING OF :  
SOLDER CONNECTION PADS  
ON A SUBSTRATE AND GUIDE  
FOR THE IMPLEMENTATION  
OF THE METHOD

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified  
application as follows:

IN THE CLAIMS

Please amend Claim 22 as follows:

22. (Amended) A guide according to claim 15, wherein the mold is made out of a  
material chosen from among stainless steel 316L with chemical deburring, or graphite, or  
Teflon, or silicon.

Please add new Claims 23-28 as follows:

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